

2 Applicable Documents

The following documents of the issue currently in effect form a part of this document to the extent specified herein.

2.1 IPC Documents¹

IPC-HDBK-001 Handbook & Guide to Supplement J-STD-001

IPC-T-50 Terms and Definitions for Interconnecting and Packaging Electronic Circuits

IPC-CH-65 Guidelines for Cleaning of Printed Boards and Assemblies

IPC-D-279 Design Guidelines for Reliable Surface Mount Technology Printed Board Assemblies

IPC-D-325 Documentation Requirements for Printed Boards

IPC-A-600 Acceptability of Printed Boards

IPC/WHMA-A-620 Requirements & Acceptance for Cable & Wire Harness Assemblies

IPC-AI-641 User's Guidelines for Automated Solder Joint Inspection Systems

IPC-AI-642 User's Guidelines for Automated Inspection of Artwork, Inner-layers, and Unpopulated PWBs

IPC-TM-650 Test Methods Manual

IPC-CM-770 Component Mounting Guidelines for Printed Boards

IPC-SM-782 Surface Mount Design Land Pattern Standard

IPC-SM-785 Guidelines for Accelerated Reliability Testing of Surface Mount Attachments

IPC-AJ-820 Assembly & Joining Handbook

IPC-CC-830 Qualification and Performance of Electrical Insulating Compound for Printed Board Assemblies

IPC-HDBK-830 Guidelines for Design, Selection and Application of Conformal Coatings

IPC-SM-840 Qualification and Performance of Permanent Solder Mask

IPC-2220 Family of Design Documents

IPC-7095 Design and Assembly Process Implementation for BGAs

IPC-7351 Generic Requirements for Surface Mount Design and Land Pattern Standard

IPC-6010-Series Family of Board Performance Documents

IPC-7711/7721 Rework, Repair and Modification of Electronic Assemblies

IPC-9691 User Guide for the IPC-TM-650, Method 2.6.25, Conductive Anodic Filament (CAF) Resistance Test (Electrochemical Migration Testing)

IPC-9701 Performance Test Methods and Qualification Requirements for Surface Mount Solder Attachments

2.2 Joint Industry Documents²

IPC J-STD-001 Requirements for Soldered Electrical and Electronic Assemblies

IPC/EIA J-STD-002 Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Wires

IPC/EIA J-STD-003 Solderability Tests for Printed Boards

J-STD-004 Requirements for Soldering Fluxes

IPC/JEDEC J-STD-020 Moisture/Reflow Sensitivity Classification for Plastic Integrated Circuit Surface Mount Devices

IPC/JEDEC J-STD-033 Standard for Handling, Packing, Shipping and Use of Moisture Sensitive Surface Mount Devices

ECA/IPC/JEDEC J-STD-075 Classification of Non-IC Electronic Components for Assembly Processes

1. www.ipc.org

2. www.ipc.org

2 Applicable Documents

2.3 EOS/ESD Association Documents³

ANSI/ESD S8.1 ESD Awareness Symbols

ANSI/ESD-S-20.20 Protection of Electrical and Electronic Parts, Assemblies and Equipment

2.4 Electronics Industries Alliance Documents⁴

EIA-471 Symbol and Label for Electrostatic Sensitive Devices

2.5 International Electrotechnical Commission Documents⁵

IEC/TS 61340-5-1 Protection of Electronic Devices from Electrostatic Phenomena - General Requirements

2.6 ASTM⁶

ASTM E29 Standard Practice for Using Significant Digits in Test Data to Determine Conformance with Specifications

2.7 Technical Publications⁷

Bob Willis Package on Package (PoP) STACK Package Assembly

3. www.esda.org

4. www.iec.ch

5. www.eia.org

6. www.astm.org

7. www.ASKbobwillis.com